

**DESCRIPTION**

The AM029NS085HPJ is available in PDFN8(5x6) package.

VDSS	RDS(ON)	ID
85V	2.9mΩ	100A

APPLICATIONS

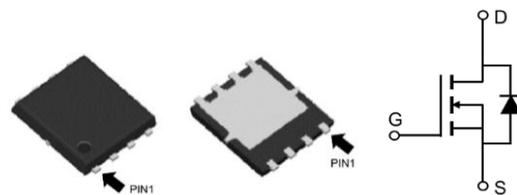
- Load Switch
- Motor Control and Drive
- Charge/Discharge for Battery Management System
- SMPS, Power Management

ORDERING INFORMATION

Package Type	Part Number	
PDFN8(5x6) SPQ: 5000pcs/Reels	PJ8	AM029NS085HPJ8VR
Note	V: Halogen free Package R: Tape & Reel	
AiT provides all RoHS products		

FEATURE

- 85V, 100A
- R_{DS(ON)} Typ.= 2.9mΩ @ V_{GS} = 10V
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% Avalanche Screened
- 100% ΔV_{ds} Tested!

PIN DESCRIPTION

Pin #	Symbol	Function
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

ABSOLUTE MAXIMUM RATINGS

T_J = 25°C, unless otherwise specified.

V _{DS} , Drain-to-Source Voltage	85V	
V _{GS} , Gate Source Voltage	±20V	
I _D , Continuous Drain Current	T _C = 25°C	Package limit 100A Silicon limit 136A
	T _C = 100°C	86A
I _{DM} , Pulsed Drain Current ⁽¹⁾	400A	
E _{AS} , Avalanche Energy, Single Pulse ⁽²⁾	676mJ	
P _D , Power Dissipation	T _C = 25°C 114W	
R _{θJC} , Thermal Resistance, Junction-to-Case	1.1°C/W	
T _{STG} , Storage Temperature Range	-55°C ~ +150°C	
T _J , Junction Temperature Range	-55°C ~ +150°C	

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. EAS condition: Starting T_J=25°C, L=0.5mH, I_b=36A



ELECTRICAL CHARACTERISTICS

T_J = 25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	85	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V	-	-	1.0	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = 20V, V _{DS} =0V	-	-	100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} = V _{GS} , I _D = 250μA	2.0	3.0	4.0	V
Static Drain-Source ON-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 70A	-	2.9	3.4	mΩ
Transconductance	g _{fs}	V _{DS} = 5V, I _D = 50A		144		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 40V, V _{GS} =0V, f=1.0MHZ	-	5621	-	pF
Output Capacitance	C _{oss}		-	923	-	
Reverse Transfer Capacitance	C _{rss}		-	10	-	
Total Gate Charge	Q _g	V _{DS} = 40V , I _D =70A V _{GS} =0V to 10V	-	85	-	nC
Gate-Source Charge	Q _{gs}		-	35	-	
Gate Drain("Miller") Charge	Q _{gd}		-	18	-	
Gate Plateau Voltage	V _{plateau}			5.1		V
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =40V, I _D = 70A R _{GEN} =3Ω, V _{GS} = 10V	-	26	-	ns
Turn-On Rise Time	t _r		-	67	-	
Turn-Off Delay Time	t _{d(off)}		-	63	-	
Turn-Off Fall Time	t _f		-	37	-	
Drain-Source Diode Characteristics and Max Ratings						
Maximum Continuous Drain to Source Diode Forward Current	I _S	-	-	-	100	A
Maximum Pulsed Drain to Source Diode Forward Current	I _{SM}		-	-	400	A
Drain to Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S = 30A	-	-	1.2	V
Reverse recovery time	t _{rr}	I _F = 70A	-	79	-	ns
Reverse recovery charge	Q _{rr}	diF/dt=100A/μs	-	110	-	nC



TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Output Characteristics

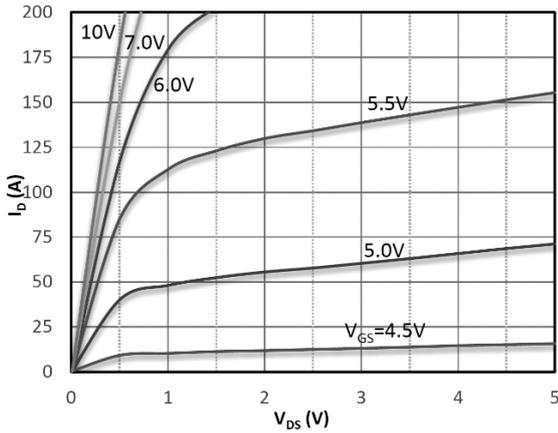


Fig 2. Typical Transfer Characteristics

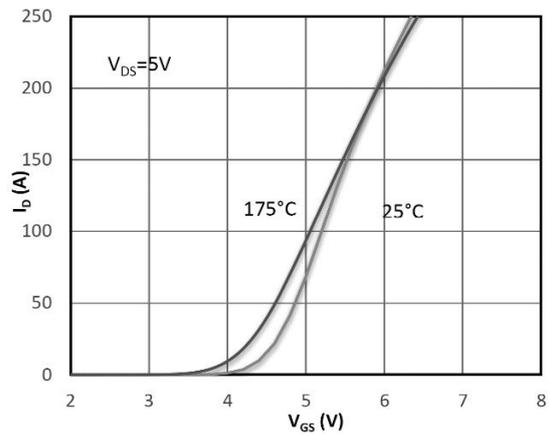


Fig 3. On resistance ($R_{DS(on)}$) vs. Drain Current

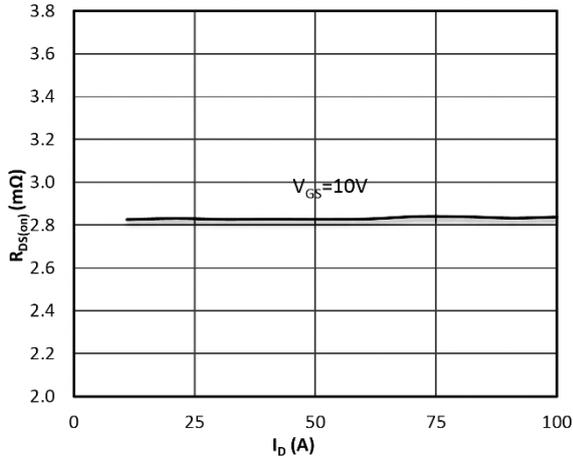


Fig 4. On resistance ($R_{DS(on)}$) vs. Gate Voltage

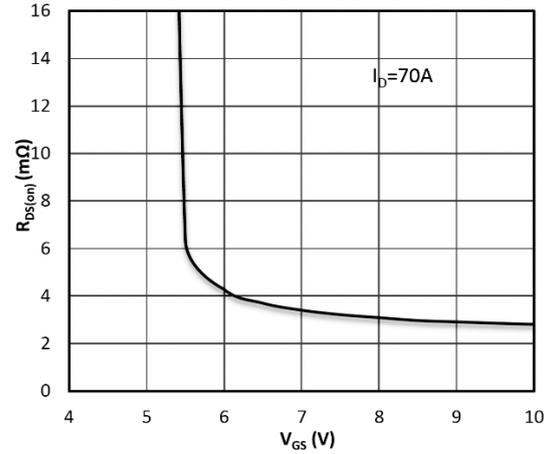


Fig 5. On resistance ($R_{DS(on)}$) vs. Temperature

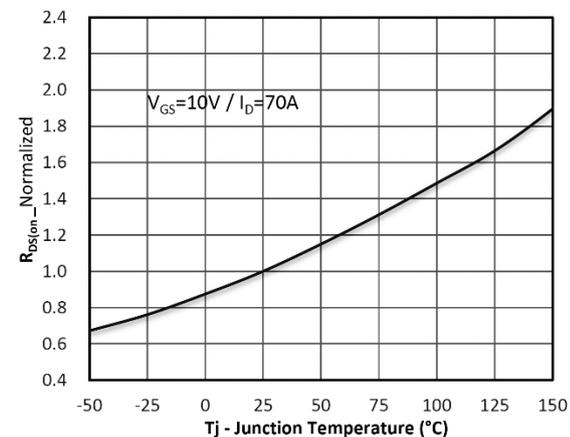


Fig 6. Capacitance Characteristics

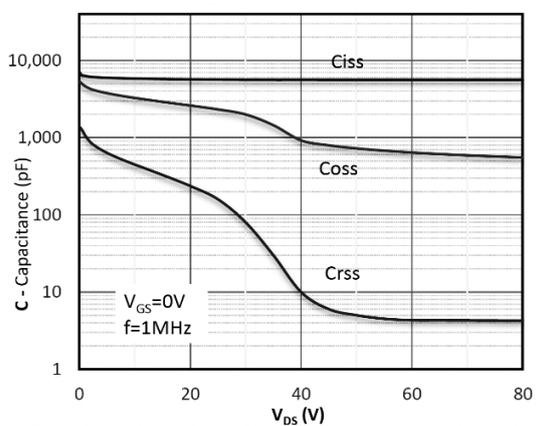




Fig 7. Gate Charge Characteristics

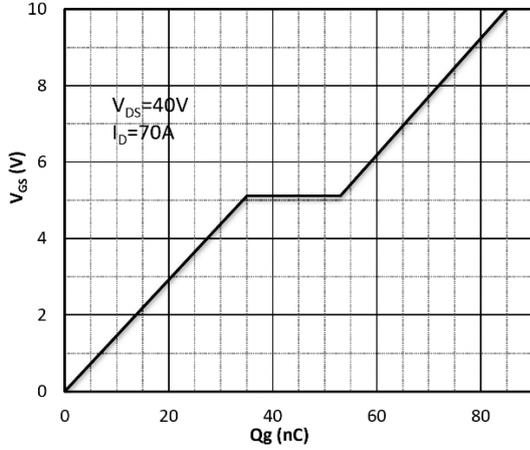


Fig 8. Body-diode Forward Characteristics

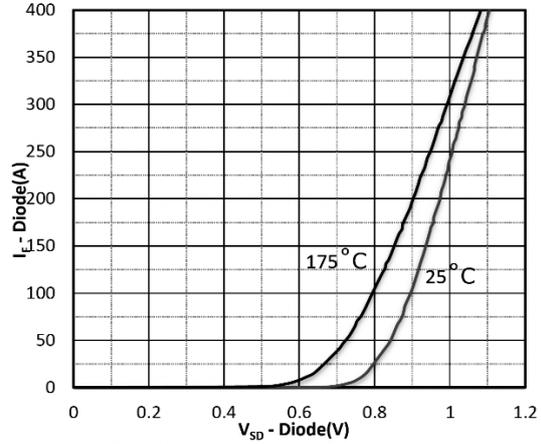


Fig 9. Power De-rating

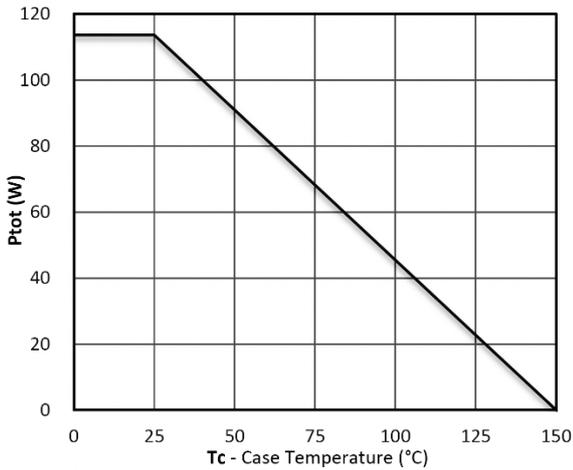


Fig 10. Current De-rating

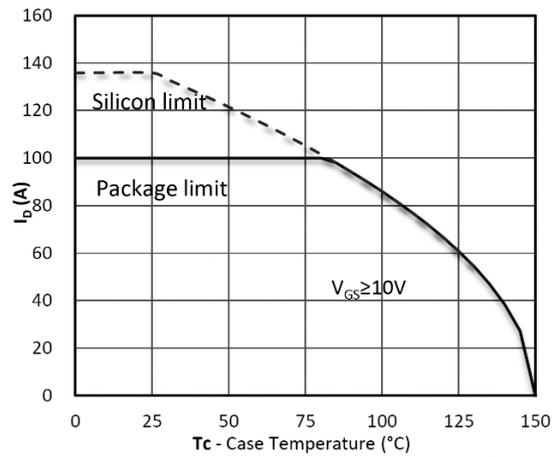


Fig11. Maximum Safe Operating Area

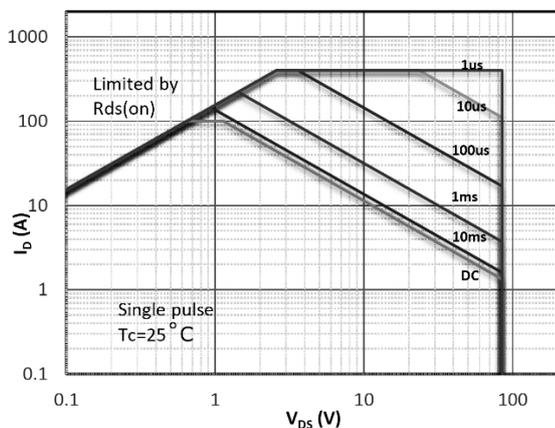


Fig 12. Max. Transient Thermal Impedance

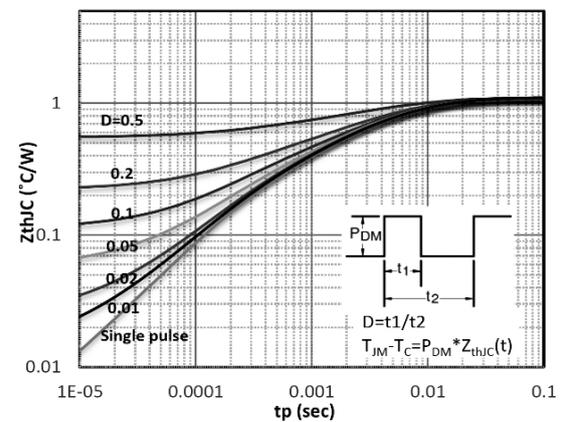




Fig 13. Gate Charge Test Circuit

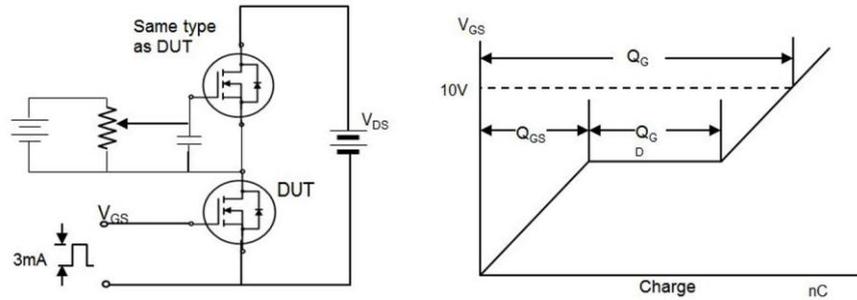


Fig 14. Resistive Switching Test Circuit & Waveform

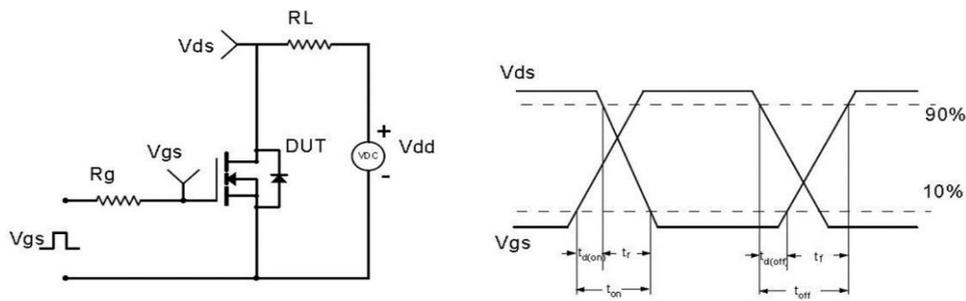


Fig 15. Unclamped Inductive Switching Test Circuit & Waveform

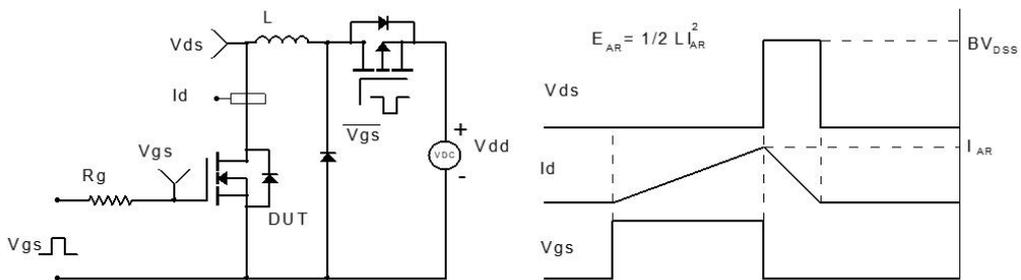
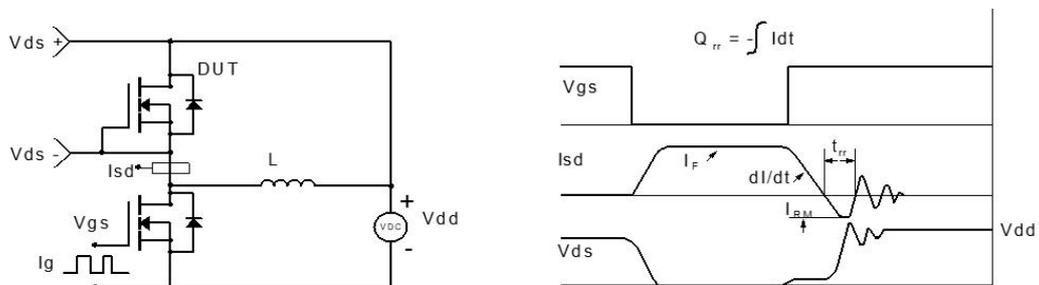


Fig 16. Diode Recovery Test Circuit & Waveform





PACKAGE INFORMATION

Dimension in PDFN8(5x6) (Unit: mm)

Symbol	Millimeters	
	Min.	Max.
A	6.000	6.200
B	4.875	4.925
b1	0.975	1.025
b2	0.246	0.262
C	5.775	5.825
D	1.245	1.295
d1	0.275	0.325
d2	0.375	0.425
E	1.725	1.825
E1	0.395	0.495
E2	3.425	3.525
E3	3.960	4.060



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